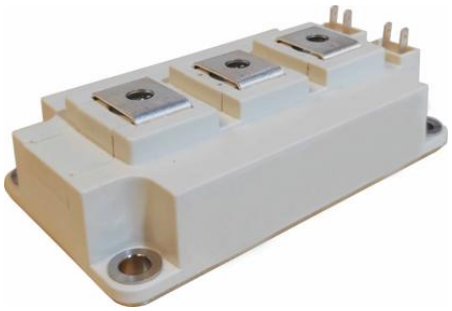
QMFF300R12EFF

1200V 300A IGBT Module

Electrical Features

- Trench/Fieldstop IGBT
- Half-bridge
- Standard package
- High short circuit capability
- Including anti-parallel FWD



Typical Applications

- Frequency converter
- UPS

IGBT，Inverter

Maximum Rated Values						
Symbol	Item	Conditions		Rating		Unit
IGBT						
V_{CES}	Collector-emitter voltage	T_{vj}=25°C		1200		V
V_{GES}	Gate-emitter voltage	-		±20		V
I_C	Collector current,DC	T_C=100°C,T_{vj}=175°C		300		A
I_{CRM}	Repetitive peak collector current	t_p=1ms		600		A
t_{SC}	Short circuit withstand time	V_{GE}=15V, V_{CC}=600V, T_{vj}≤150°C		10		μs
P_{tot}	Total power dissipation	T_C=25°C,T_{vj}=175°C		1612		W
Characteristics Values						
Symbol	Item	Conditions		Values		Unit
IGBT				Min.	Typ. Max.	
I_{CES}	Collector-emitter cut-off current	V_{CE}=1200V,V_{GE}=0V,T_{vj}=25°C		-	- 1	mA
I_{GES}	Gate leakage current	V_{CE}=0V,V_{GE}=20V,T_{vj}=25°C		-	- 250	nA
$V_{GE(th)}$	Gate-emitter threshold voltage	I_C=11.5mA,V_{CE}=V_{GE},T_{vj}=25°C		5	5.86 7	
V_{CEsat}	Collector-emitter saturation voltage	I_C=300A V_{GE}=15V	T_{vj}=25°C	-	1.75 -	V
			T_{vj}=125°C	-	- -	
			T_{vj}=150°C	-	- -	
C_{ies}	Input capacitance	V_{CE}=25V,V_{GE}=0V f=1MHz,T_{vj}=25°C		-	19.4 -	nF
C_{res}	Reverse transfer capacitance			-	0.6 -	
Q_G	Gate charge	V_{CC}=600V, I_C=300A, V_{GE}=15V		-	2.4 -	μC

$t_{d(on)}$	Turn-on delay time	V_{CC}=600V, I_C=300A, V_{GE}=±15V, $R_{G(on)}$=5.1 Ω, $R_{G(off)}$=2 Ω, Inductive load	T_{vj}=25°C	-	416.6	-	ns
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
t_r	Rise time		T_{vj}=25°C	-	111.3	-	
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
$t_{d(off)}$	Turn-off delay time		T_{vj}=25°C	-	359.8	-	
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
t_f	Fall time		T_{vj}=25°C	-	115.8	-	
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
E_{on}	Turn-on energy (per pulse)		T_{vj}=25°C	-	35.09	-	mJ
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
E_{off}	Turn-off energy (per pulse)		T_{vj}=25°C	-	21.3	-	
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
R_{thJC}	Thermal resistance,junction to case	per IGBT		-	-	0.093	K/W
R_{thCH}	Thermalresistance,case to heatsink	per IGBT/ λgrease=1W/(m·K)		-	0.032	-	K/W
T_{vjop}	Temperature under switching conditions			-40		150	°C

Diode，Inverter
Maximum Rated Values

Symbol	Item	Conditions	Rating	Unit
V_{RRM}	Repetitive peak reverse voltage	T_{vj}=25°C	1200	V
I_F	Forward current,DC		300	A
I_{FRM}	Repetitive peak forward current	t_p=1ms	600	A

Characteristic Values

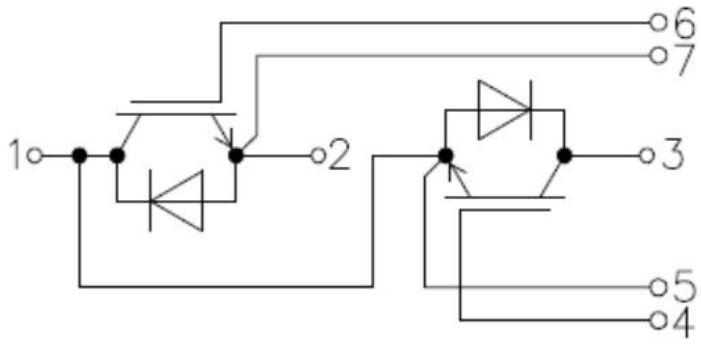
V_F	Continuous forward voltage	I_F=300A V_{GE}=0V	T_{vj}=25°C	-	1.83	-	V
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
I_{RM}	Peak reverse recovery current	V_R=600V I_F=300A di_F/dt=-3700A/μs	T_{vj}=25°C	-	170	-	A
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
t_{rr}	Reverse recovery time		T_{vj}=25°C	-	153.8	-	ns
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
Q_r	Repetitive peak forward current		T_{vj}=25°C	-	20.9	-	μC
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	
E_{rec}	Recovered charge		T_{vj}=25°C	-	8.59	-	mJ
			T_{vj}=125°C	-	-	-	
			T_{vj}=150°C	-	-	-	

R_{thJC}	Thermal resistance, junction to case	per diode	-	-	0.15	K/W
R_{thCH}	Thermalresistance,case to heatsink	per diode/ λgrease=1W/(m·K)	-	0.052	-	K/W
T_{vjop}	Temperature under switching conditions		-40		150	℃

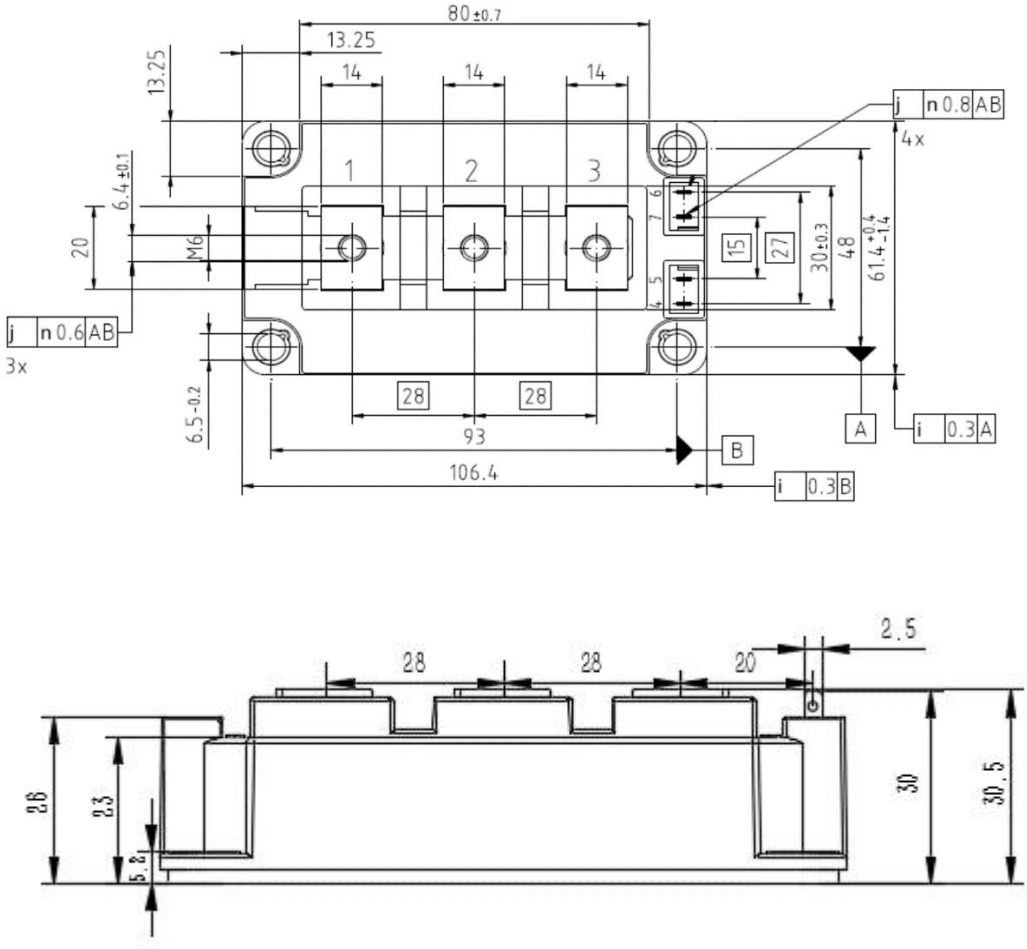
Module

Symbol	Item	Conditions	Rating			Unit
V_{ISOL}	Isolation voltage	Terminals to baseplate，RMS,f=50Hz,t=1min	2500			V
-	Material of module baseplate	-	Cu			-
-	Internal isolation	Basic insulation(class 1, IEC 61140)	Al_2O_3			-
T_{stg}	Storage temperature	-	-40~125			℃
Symbol	Item	Conditions	Values			Unit
			Min.	Typ.	Max.	
M	Mounting torque for module mounting	Screw M6	3.0	-	6.0	Nm
	Terminal connection torque	Screw M6	2.5	-	5.0	Nm
ds	Creepage distance	Terminal to terminal	-	23	-	mm
		Terminal to base plate	-	29	-	
da	Clearance	Terminal to terminal	-	11	-	mm
		Terminal to base plate	-	23	-	
m	Weight	-	-	315	-	g

Circuit diagram headline



Package outlines（Unit：mm）



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